

**South Dakota School of Mines and Technology**

**INVENTION DISCLOSURE FORM**

Date of submission: \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

 **1. TITLE OF INVENTION** (a short but sufficiently descriptive title to identify the general nature of the invention.)

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| **2.** | **DESCRIPTION OF THE INVENTION***Please Note:* 1. *The purpose of your description is to enable a person with similar skills in your field to be able to make and use the invention you describe.*
2. *Please do not withhold any key elements of the invention (you are obliged to describe the best way of making and using the invention known to you at the time of submission).*
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| **2.1** | **Field of the Invention:** *A sentence of brief paragraph identifying the general field of technology to which the invention relates and keywords that will help define publication and patent searches.*  |
| **2.2** | **Summary of the Invention:***A brief paragraph (similar to the abstract of a scientific paper) describing the key feature(s) of the invention with some background context.*  |
| **2.3** | **Brief Description of the Drawings (if any):** *Listing of the captions of each drawing or figure relevant to the invention that you have attached to this invention disclosure.*  |
| **2.4** | **Detailed Description of the Preferred Embodiments:** 1. *A full description of the invention including background, preferred mode of practice of the invention i.e., basic nature or structure of invention, how it works with reference to relevant attached drawings, etc. (this can be a separate attachment).*
2. *What problem(s) does the invention solve? What advantages does this invention have over existing methods, devices, or materials?*
3. *What are the possible specific industrial applications?*
4. *Does your invention possess any disadvantages or limitations? Can they be overcome? What are the competing ways to solve the same problem(s)?*
 |
| **2.5** | **Modifications of the Preferred Embodiments (if any):***Discussion of other modes of practice of the invention.*  |
| **2.6** | **References:** *Please list literature references that most closely describe your invention.* *List of references cited in the write-up.*  |

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| **3.** | **SOURCES OF SUPPORT AND GRANT(S) RELATING TO INVENTION:** *Please identify all outside agencies, organizations, or companies that provide funding to the research that led to the conception of the invention. Obligations of the research sponsor(s) will have to be met if patent protection and/or licensing of the technology is pursued. Please also disclose any other contractual obligations entered into to come up with the invention including collaborations, research contracts, material transfers, etc.*  |
| Was the invention conceived or first actually reduced to practice in the performance of work funded, in whole or in part, by any federal grant(s), contract(s), or subaward(s)? If yes, list below. Yes No  |
| **Source(s) of Funding** |
| **Sponsor Name:** **Grant or Contract No.** Title of Project Funded:Collaborators (if any):Was there a formal agreement signed? Yes No Have university resources or facilitiesbeen used? Yes No If yes, what University(ies): | **Sponsor Name:** **Grant or Contract No.** Title of Project Funded:Collaborators (if any):Was there a formal agreement signed? Yes NoHave university resources or facilitiesbeen used? Yes NoIf yes, what University(ies): |
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| **4.** | **DATES OF CONCEPTION & PUBLIC DISCLOSURE:** *Please defer publication if you think that you may have patentable subject matter. Public disclosure of an invention before filing a patent application will render the invention not applicable in most countries.*  |
|  | Date of documented conception of invention: |
|  | Date of first public disclosure that describes invention, if any: Attach copies of material if possible. |
|  | Do you intend to disclose the invention publicly in the near future? Yes NoIf yes, when and where?  |
|  | Has this invention been reduced to practice? Yes No |
|  | Please indicate the status and intention for your invention. (You may select more than one box) Project ongoing Looking for collaborators for further R&D For information only  Project ended Ready for commercialization Application to file patent Further R&D Others (please specify):  |

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| **5.** | **CONTRACTUAL OBLIGATIONS:** *(Research Collaborations Agreements, Material Transfer Agreements, Etc.)* |
|  | (i)Title of Collaboration: (ii) Reference Number: (iii) Name of Collaborator or Provider of Material: (iv) Relevant Details of Collaboration or Material:  |
| **6.** | **COMMERCIALIZATION:** *Please identify any potential licensees or collaborators interested in the invention.*  |
|  | List companies or organizations, if any, that could be interested in using this invention.  |
|  | Do you have plans to spin off a company based on your invention? Yes No |
|  | Would you be willing to participate in the marketing of this invention by explaining it to potential commercial partners? Yes No |

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| 7. | **SOFTWARE DEVELOPMENT** *(If your invention involves or includes software, please answer the following questions. Otherwise, skip this section.)* |
|  | Is the software standalone? If not, list associated software that is required for the invention to work.  |
|  | What language is the software developed in and what platforms is it designed for delivery on? List the minimum hardware specifications required.  |
|  | Was any of the source code obtained under an open source license (I.e. BSD, GPL, Apache, etc.) or from any other sources? Yes NoIf yes,1. Please provide a list of the sources:
2. Explain how the sources listed above have been used in the invention:
 |
|  | Are there any third party rights assocated with the invention of the software? List grants or contracts if any, with third parties.  |
|  | Is the software an improvement of existing software? Has a license been obtained on the existing software? Provide details.  |
|  | Is the software a proof-of-concept, a demonstration, prototype or fully functional end user version?  |

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| 8. | **INVENTORS’ PARTICULARS & DECLARATIONS** *Original signatures are required. Inventorship is defined as person(s) who contributes, individually or jointly, to the inventive steps that make the invention workable. Do not list any inventor gratuitously. The rules for inclusion are not the same as a scientific publication.*  |
| I/we hereby declare to the best of my/our knowledge the information provided in this invention disclosure form are true and correct. Note, by signing this form the undersigned inventors acknowledge and agree that they are bound by SDBOR Intellectual Property Policy 4:34.  |
| **Lead Inventor** |
|  | Title: Mr. Ms. Dr. Asst Prof. Assoc Prof. Prof \* |
| Name:  | % of Contribution:  | Citizenship:  |
| University Positions:  Faculty Post-Doc Research Scientist  Undergraduate Student Graduate Student Technician Other: \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_ | Staff ID or Student No.:  |
| Faculty/Department/Institution:  | Phone Number: Mobile Number:  |
| Mailing Address:  | Home Address (if different): |
| Email:  |
| Signature & Date:  |

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| **Co-Inventor**  |
|  | Title: Mr. Ms. Dr. Asst Prof. Assoc Prof. Prof \* |
| Name:  | % of Contribution:  | Name:  |
| University Positions:  Faculty Post-Doc Research Scientist  Undergraduate Student Graduate Student Technician Other: \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_ | Staff ID or Student No.:  |
| Faculty/Department/Institution:  | Phone Number: Mobile Number:  |
| Mailing Address:  | Home Address (if different): |
| Email:  |
| Signature & Date:  |

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| --- |
| **Co-Inventor**  |
|  | Title: Mr. Ms. Dr. Asst Prof. Assoc Prof. Prof \* |
| Name:  | % of Contribution:  | Name:  |
| University Positions:  Faculty Post-Doc Research Scientist  Undergraduate Student Graduate Student Technician Other: \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_ | Staff ID or Student No.:  |
| Faculty/Department/Institution:  | Phone Number: Mobile Number:  |
| Mailing Address:  | Home Address (if different): |
| Email:  |
| Signature & Date:  |
| **Co-Inventor**  |
|  | Title: Mr. Ms. Dr. Asst Prof. Assoc Prof. Prof \* |
| Name:  | Name:  | % of Contribution:  |
| University Positions: Faculty Post-Doc Research Scientist Undergraduate Student Graduate StudentTechnician Other: \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_ | University Positions:  Faculty Post-Doc Research Scientist  Undergraduate Student Graduate Student Technician Other: \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_ |
| Faculty/Department/Institution:  | Faculty/Department/Institution:  |
| Mailing Address:  | Mailing Address:  |
| Email:  |
| Signature & Date:  |

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| *\*Please attach pages as required for additional inventors. All inventors will need to sign the disclosure. If any co-inventor is not an employee of SDSM&T, please provide their institution and the inventor’s full address.* |

Please deliver a Signed Original to:**Economic.Development@sdsmt.edu**